

Title (en)

SLIDING PLATE AND FLOOR PLATE FOR TURNOUT

Title (de)

SCHIEBEPLATTE UND BODENPLATTE ZUM HERAUSDREHEN

Title (fr)

PLAQUE DE GLISSEMENT ET PLAQUE DE PLANCHER POUR AIGUILAGE

Publication

**EP 2946855 A1 20151125 (EN)**

Application

**EP 14741082 A 20140114**

Priority

- JP 2013005756 A 20130116
- JP 2014050443 W 20140114

Abstract (en)

Provided are: a sliding plate, the thickness and performance of which can be easily adjusted; and a floor plate for a turnout, using the sliding plate. A sliding plate (3) is provided with a backing material (31) comprising a steel plate or the like, a punching metal (32) disposed on the backing material (31), and a sintered metal powder layer (33) formed on the upper surface (310) of the backing material (31) so as to cover the punching metal (32). The sintered metal powder layer (33) is formed by subjecting an alloy powder for sintering to sintering and rolling, and is impregnated with a lubricating resin through heat melting. The sintered metal powder layer (33) formed on a metal area (321) of the punching metal (32) has undergone high-pressure compression and therefore exhibits a high sintered density and excellent resistance to impact, load and wear. Meanwhile, the sintered metal powder layer (33) formed in empty spaces (322) of the punching metal (32) has undergone low-pressure compression and therefore exhibits a low sintered density and a high impregnation rate of the lubricating resin, thus attaining excellent lubrication.

IPC 8 full level

**B22F 7/04** (2006.01); **E01B 7/00** (2006.01)

CPC (source: EP US)

**B22F 7/04** (2013.01 - EP US); **C10M 169/041** (2013.01 - US); **E01B 7/02** (2013.01 - EP US); **E01B 7/26** (2013.01 - US);  
**B22F 2999/00** (2013.01 - EP US)

Cited by

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AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 2946855 A1 20151125**; **EP 2946855 A4 20160831**; CN 104994977 A 20151021; JP 2014136899 A 20140728; JP 6141642 B2 20170607;  
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